MA2SV04

Silicon epitaxial planar type

For VCO

■ Features

- ullet Good linearity and large capacitance-ratio in C_D V_R relation
- ullet Small series resistance r_D
- SS-Mini type package, allowing downsizing of equipment and automatic insertion through the taping package

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Reverse voltage	V_R	6	V	
Junction temperature	T _j	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	



Marking Symbol: 5

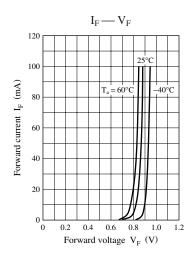
■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

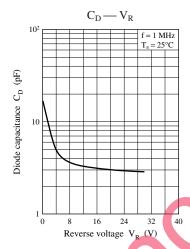
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse current	I_R	$V_R = 5 \text{ V}$			10	nA
Diode capacitance	$C_{D(1V)}$	$V_R = 1 \text{ V, f} = 1 \text{ MHz}$	10.0		11.1	pF
	$C_{D(3V)}$	$V_R = 3 \text{ V}, f = 1 \text{ MHz}$	5.8		6.4	
Series resistance *	r_{D}	$V_R = 3 \text{ V, f} = 470 \text{ MHz}$			0.35	Ω

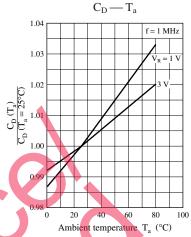
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

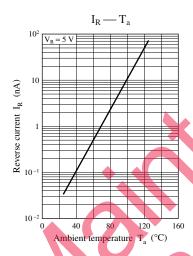
- 2. Absolute frequency of input and output is 470 MHz.
- 3. *: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER

Publication date: March 2004 SKD00016CED 1









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